

AMENDMENTS TO THE SPECIFICATION

On page 5, please replace the second paragraph after the heading “Detailed Description of the Invention”, with the following amended paragraph:

As can be seen in the Figure, the semiconductor device of the invention comprises a substrate (1) and a semiconductor element (2) mounted thereon through a bump bonding part (3), wherein the semiconductor element (2) has been encapsulated by coating the back (4) and the corner edges of the back (5) of the semiconductor element (2) with a thermosetting sheet material (6) having tackiness.